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(54) **METHOD FOR PRODUCING MULTI-LAYER
CIRCUIT BOARDS**

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(57) **ABSTRACT**

A method for producing multi-layer circuit boards, wherein, in an assembly method step, multiple functional layers and at least one insulating layer of a circuit board to be produced are arranged in layers between a tool lower part and a tool upper part of a multi-part tool. At least one measuring transducer is positioned between the tool upper part and the tool lower part such that the measuring transducer is in contact with at least one functional layer and/or insulating layer of the circuit board to be produced. The tool is then introduced into a thermo-compression chamber. The tool upper part and the tool lower part, along with the multiple functional layers and the at least one insulating layer and the measuring transducer provided between same, are then pressed against one another in the thermo-compression chamber and heated and measurement values are detected with the measuring transducer.

